

Multilayer Ceramic Chip Capacitors

▼ more

C2012X7S1A226M125AC



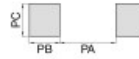
TDK item description ? C2012X7S1A226MT****

Applications Commercial Grade

Feature General General (Up to 75V)

Series C2012 [EIA 0805]

Status Production



Images are for reference only and show exemplary products.

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Documents

- [Catalog](#) Update
- [Specification](#)
- [RoHS Certificate](#) Update
- [SVHC/REACH Certificate](#)
- [Sample Kits](#)

Technical Support Tools

- [S-parameter](#)
- [SPICE Netlist \(Simple\)](#)
- [SPICE Netlist \(Precision\)](#)
- [Equivalent Circuit Model](#)
- [DC Bias/Superimposition Model \(HSPICE\)](#)

Pages related to the series to which this product belongs

- [Description of icons | Environment](#)

Size	
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	22µF ±20%
Rated Voltage	10VDC
Temperature Characteristic ?	X7S(±22%)
Dissipation Factor (Max.)	10%
Insulation Resistance (Min.)	4MΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)



C2012X7S1A226M125AC

Configuration

Capacitance

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Configuration

Temperature Characteristic

no data available

Configuration

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Configuration

DC Bias Characteristic

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Configuration

Ripple Temperature Rising

C2012X7S1A226M125AC(100k Hz) C2012X7S1A226M125AC(500k Hz) C2012X7S1A226M125AC(1M Hz)

Configuration



Selection Guides Search by Part No. Search by Characteristics Distributor Inventory Check Cross Reference

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- Capacitors >
- Inductors (Coils) >
- EMC Components >
- RF Components and Modules >
- Voltage / Current / Temperature Protection Devices >
- Sensors and Sensor Systems >
- Ceramic Switching / Heating, Piezo Components, >

Buzzers and Microphones

Transformers >

Ferrites and Accessories >

Noise Suppressing / Magnetic Sheet >

Anechoic Chambers and Radio Wave Absorbers >

Power Supplies >

Magnets >

Flash Storages >

Wireless Power Transfer >

FA Systems >

Transparent Conductive Film >

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